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ABSTRACT(73) Assignee: **PEGATRON CORPORATION,**
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An electronic device includes a housing, a heat conductive portion, a circuit board, a fin set, and a fan. The housing has an accommodating space. The heat conductive portion is disposed in the accommodating space, and divides the accommodating space into a first space and a second space. The circuit board is disposed in the first space and includes a heat source. The heat source generates heat and is thermally coupled to the heat conductive portion. The fin set is disposed in the second space and thermally coupled to the heat conductive portion. The fan is disposed in the second space and located on one side of the fin set. The fan is adapted to guide an airflow through the fin set to discharge the heat generated by the heat source from the housing.

